

# SimpleLink<sup>™</sup> CC1200 AES Operation

Martin Brinkmann

#### ABSTRACT

This application report shows how to use the Advanced Encryption Standard (AES) capability of the SimpleLink CC1200 low-power high performance transceiver. It shows how to do stand-alone CBS block operations and how to do in-line CTR mode security operations on TX/RX FIFO content. The application report assumes that the reader is familiar with the basic concepts of AES and the different commonly used modes such as Counter (CTR) and Cipher Block Chaining (CBC).

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## 1 Introduction

This application report describes the key elements of the SimpleLink CC1200 transceiver AES encryption module. The AES encryption module is typically used to encrypt RF communication, to provide a secure RF link. The main objective of this application report is to explain how to utilize the CC1200 AES encryption module to do AES counter mode (CTR) encryption and decryption.

## 1.1 Acronyms

Acronym	Description
AES	Advanced Encryption Standard
CBC	Cipher Block Chaining
CTR	Counter
FIFO	First In First Out
IV	Initialization Vector
RF	Radio Frequency
RX	Receive
SPI	Serial Peripheral Interface
TX	Transmit

#### Table 1. Acronyms Used in This Document

#### 2 Background

The CC1200 contains an AES module that can be used to do stand-alone AES block operations or to do security operations on the FIFO content. The AES module uses cipher block chaining (CBC) for block operations. When using AES operations on the TX FIFO and RX FIFO content, the AES module uses CBC block operation to do CTR encryption and decryption.

#### 3 Address Space Used by the AES Module

The CC1200 uses two different parts of the extended memory space to do AES operations; the two memory spaces are the AES workspace and the AES command workspace. Different serial peripheral interface (SPI) access needs to be used to get access to the two memory spaces. Figure 1 shows the SPI memory map for the different SPI access types. Section 3.1 and Section 3.2 provide more details about the different workspaces and how they are used for AES operations.

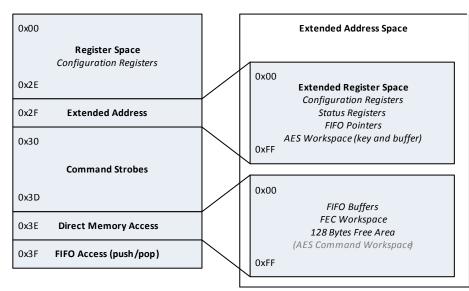


Figure 1. CC1200 Memory Space



# 3.1 AES Workspace

The AES workspace is in the extended memory section. It holds the 128-bit AES key and the 128 data buffer for block operations. The extended register space needs to be accessed to use the AES workspace. In the extended register space the AES key is located from address 0xE0 to 0xEF and the data buffer from address 0xF0 to 0xFF. For more details, see the *CC120X Low-Power High Performance Sub-1 GHz RF Transceivers User's Guide* (SWRU346).

# 3.2 AES Command Workspace

The AES command workspace is used for AES parameters when doing AES operations on FIFO content. It holds the Initialization Vector (IV)/nonce along with length information and pointers to the FIFO content to be encrypted or decrypted. The parameters used are described in Section 5.2. The AES command workspace can be accessed through the direct memory access command described in Table 2.

Access Type	Command/Address Byte	Description
Direct Access to 128 Bytes Free Area (AES Command Workspace)	Command: R/W; <sup>-</sup> B 1 1 1 1 1 0 Address: A <sub>7</sub> A <sub>6</sub> A <sub>5</sub> A <sub>4</sub> A <sub>3</sub> A <sub>2</sub> A <sub>1</sub> A <sub>0</sub>	This access mode starts with a specific command (0x3E) which makes it possible to access 128 bytes of free memory.
	SPI_DIRECT_ACCESS_CFG in SERIAL_STATUS must be 1	The first byte following this command is interpreted as the address. The next byte
	0x80 ≤ A7 - 0 ≤ 0xFF	is read/written to this address. If burst is enabled, consecutive bytes will be read/written by incrementing the address.

## Table 2. SPI Access Type for AES Operation

# 4 AES Block Operation

The CC1200 AES module can be used to do CBC encryption on 128-bit data blocks. The MCU needs to write the data block to the CC1200 over SPI in order to do block operations. After the encryption is completed the MCU needs to read the encrypted data back. Section 4.1 describes the steps needed to do block operation on 128-bit data blocks and Example 1 shows an example on how this can be done in the software. Note that the CC1200 is only capable of CBC encryption. For both encryption and decryption CTR mode must be used.

# 4.1 AES Block Operation Procedure

The following steps must be done to encrypt a 128-bit data block using CBC:

- 1. Write the 128 bit long AES key to the key location in the AES workspace.
- 2. XOR plain text with initialization vector or cipher text from previous block.
- 3. Write the 128 bit long XOR'ed data block to the buffer location in the AES workspace.
- 4. Execute encryption by setting the AES\_AES\_RUN bit to 1. The bit will be set low by HW when encryption is finished.
- 5. Read the encrypted data block.

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**AES FIFO Operations** 

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### Example 1. AES Block Operation Procedure

```
#define AES_BLOCK_SIZE
                            16
static uint8 writeByte;
static uint8 plainData[AES_BLOCK_SIZE];
static uint8 aesKey[AES_BLOCK_SIZE];
static uint8 dataBlock[AES_BLOCK_SIZE];
static uint8 initalizationVector[AES_BLOCK_SIZE];
static uint8 cipherBlock[AES_BLOCK_SIZE];
// 1) Write 128 bit AES key into key memory input
ccl20xSpiWriteReg(CCl20X_AES_KEY, aesKey, AES_BLOCK_SIZE);
// 2) XOR initialization vector with plain text data
for (uint8 i = 0; i < AES_BLOCK_SIZE; i++)</pre>
{
  dataBlock[i] = (plainData[i] ^ initalizationVector[i]);
}
// 3) Write 128 bit data block into plain data memory input
ccl20xSpiWriteReg(CCl20X_AES_BUFFER, dataBlock, AES_BLOCK_SIZE);
// 4) Execute AES RUN
writeByte = 0 \times 01;
ccl20xSpiWriteReg(CCl20X_AES, &writeByte, 1);
// Wait for AES operation to finish
while((writeByte & 0x01)== 0x01 ){
 cc120xSpiReadReg(CC120X_AES, &writeByte, 1);
}
// 5) Read cipher block from AES buffer
cc120xSpiReadReg(CC120X_AES_BUFFER, cipherBlock, AES_BLOCK_SIZE);
```

# 5 AES FIFO Operations

The AES module can also be used to do AES operations directly on data placed in the TX and RX FIFO. The AES commands used on the FIFO content will encrypt and decrypt using AES CTR. The following section describes the different AES commands and AES parameters needed to do AES FIFO operations.

# 5.1 AES Commands

The CC1200 has two AES high level commands that can be used to do AES operation on data placed in the TX and RX FIFO. Table 3 shows the different AES commands. The two commands are set in the AES\_COMMANDS bit field in the MARC\_SPARE register and will be executed by an SIDLE command strobe.

Table 3. AES	S Commands
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MARC_SPARE.AES_COMMANDS	Command	Description
0x09	AES_TXFIFO	AES CTR on the TX FIFO content
0x0A	AES_RXFIFO	AES CTR on the RX FIFO content

# 5.2 AES Parameters

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Two parameters are needed for the AES module to perform FIFO operations, a pointer to the first byte in the FIFO and the number of bytes to be encrypted or decrypted. Section 5.2.1 and Section 5.2.2 describe the two parameters needed for each operation and where in the memory these parameters must be written to in the AES workspace. This can be done using the direct memory access shown in Table 2.

### 5.2.1 AES TX FIFO

The AES\_TXFIFO command is used to do CTR encryption on the TX FIFO content. Parameters needed to be initialized are shown in Table 4. The initialization vector/nonce is located in memory location 0x80 in the AES command workspace.

Table 4. AE	S TX FIFO	Parameters
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Address	Parameter
0xF0	Pointer to first entry in the TXFIFO to encrypt (the packet must always be written to a flushed TXFIFO meaning that the first byte in the packet is at location 0x00)
0xF2	Number of bytes in the TXFIFO that should be encrypted

# 5.2.2 AES RX FIFO

The AES\_RXFIFO command is used to do CTR decryption on the RX FIFO content. Parameters needed to be initialized are shown in Table 5. The initialization vector/nonce is located in memory location 0x80 in the AES command workspace.

## Table 5. AES RX FIFO Parameters

Address	Parameter
0xF0	Pointer to first entry in the RXFIFO to decrypt (the RXFIFO must be flushed before the packet is received meaning that the first byte in the packet is at location 0x00)
0xF2	Number of bytes in the RXFIFO that should be decrypted

# 5.3 AES TX/RX FIFO Operation

Section 5.3.1 describes how to encrypt TX FIFO content. Example 2 provides an example on how this can be done in the software.

## 5.3.1 TX FIFO Encryption

- 1. Make sure the radio is in IDLE state.
- 2. Flush the TXFIFO using the SFTX command strobe.
- 3. Write the packet to the TXFIFO.
- 4. Set the MARC\_SPARE.AES\_COMMAND = 0x09 (AES\_TXFIFO).
- 5. Write the 128 bit long AES key to the key location in the AES workspace (AES\_KEY15 is the 7 MSB and starts at address 0x2FE0).
- 6. Set SERIAL\_STATUS.SPI\_DIRECT\_ACCESS\_CFG = 1.
- 7. Write the AES TXFIFO parameters (see Table 4) to the AES command workspace using direct memory access.
- 8. Write the nonce to address 0x80 in the AES command workspace using direct memory access.
- 9. Set SERIAL\_STATUS.SPI\_DIRECT\_ACCESS\_CFG = 0.
- 10. Strobe SIDLE to execute the AES\_TXFIFO command.
- 11. A falling edge on GPIO0 indicates that the operation is done (if IOCFG0. PIO0\_CFG = AES\_COMMAND\_ACTIVE (22)) and an STX strobe can be issued.

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#### Example 2. AES TX FIFO Encryption

```
#define AES_BLOCK_SIZE
                            16
#define PKTLEN
                    30
static uint8 writeByte;
uint8 txBuffer[PKTLEN];
uint8 ramData[4];
static uint8 aesKey[AES_BLOCK_SIZE];
static uint8 nonce[AES_BLOCK_SIZE];
^{\prime\prime} 1) Be sure the radio is in IDLE (radio must be in IDLE to execute AES commands)
trxSpiCmdStrobe(CC120X_SIDLE);
// 2) Flush TXFIFO
trxSpiCmdStrobe(CC120X_SFTX);
// 3) Write packet to TXFIFO
ccl20xSpiWriteTxFifo(txBuffer,sizeof(txBuffer));
// 4) Set MARC_SPARE:AES_COMMAND to 0x09 (AES TXFIFO)
writeByte = 0x09;
ccl20xSpiWriteReg(CCl20X_MARC_SPARE, &writeByte,1);
// 5) Write AES key to extendend register space address 0{\tt xE0}
ccl20xSpiWriteReg(CCl20X_AES_KEY15, aesKey, sizeof(aesKey));
// 6) Enable SPI direct memory access (SPI_DIRECT_ACCESS_CFG = 1)
writeByte = 0x20;
ccl20xSpiWriteReg(CCl20X_SERIAL_STATUS,&writeByte,1);
// 7) Write AES TXFIFO command
// TXFIFO start pointer @ 0x3EFO (extended memory space, Free Area 0x3EFO) (word length 2B)
// TXFIFO packet size @ 0x3EF2 (extended memory space, Free Area 0x3EF2) (word length 2B)
ramData[0] = 0x00;
                               // TXFIFO start pointer
ramData[1] = 0x00;
                               // zero-pad due to word write in ram
ramData[2] = (PKTLEN+1);
                               // TXFIFO byte size
ramData[3] = 0x00;
                                // zero-pad
trx16BitRegAccess((RADIO_BURST_ACCESS|RADIO_WRITE_ACCESS),0x3E,0xF0,ramData,sizeof(ramData));
// 8) Write nonce vector (16B) to 0x3880 extended memory space, Free Area 0x2E80
// This vector has to be written byte reversed to what will be put in the AES BUFFER.
// AES command will rotate the vector on execution
trx16BitRegAccess((RADIO_BURST_ACCESS|RADIO_WRITE_ACCESS),0x3E,0x80,nonce,sizeof(nonce));
// 9) Disable SPI direct memory access (SPI_DIRECT_ACCESS_CFG = 0)
writeByte = 0x00;
ccl20xSpiWriteReg(CCl20X_SERIAL_STATUS,&writeByte,1);
// 10) Execute AES command by issuing IDLE strobe (radio must be in IDLE state already)
trxSpiCmdStrobe(CC120X_SIDLE);
// 11) Wait for GPIOO to go low, indicating command finished
// Assumes AES_COMMAND_ACTIVE(0x16) on GPI00 sets aesSemaphore on falling edge interrupt
while(!aesSemaphore);
```

### 5.3.2 RX FIFO Decryption

Section 5.3.2 describes how to decrypt RX FIFO content. Example 3 provides an example on how this can be done in the software.

- 1. Make sure the radio is in IDLE state.
- 2. Flush the RXFIFO using the SFRX command strobe.
- 3. Issue an SRX strobe and wait for a packet to be received.
- 4. Set the MARC\_SPARE.AES\_COMMAND = 0x0A (AES\_RXFIFO).
- 5. Write the 128 bit long AES key to the key location in the AES workspace (AES\_KEY15 is the 7 MSB and starts at address 0x2FE0).
- 6. Set SERIAL\_STATUS.SPI\_DIRECT\_ACCESS\_CFG = 1.
- 7. Write the AES RXFIFO parameters (see Table 5) to the AES command workspace using direct memory access.
- 8. Write the nonce to address 0x80 in the AES command workspace using direct memory access.
- 9. Set SERIAL\_STATUS.SPI\_DIRECT\_ACCESS\_CFG = 0.
- 10. Strobe SIDLE to execute the AES\_RXFIFO command.
- 11. A falling edge on GPIO0 indicates that the operation is done (if IOCFG0. GPIO0\_CFG = AES\_COMMAND\_ACTIVE (22)) and the RX FIFO can be read.

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#### Example 3. AES RX FIFO Decryption

```
#define AES_BLOCK_SIZE
                            16
#define PKTLEN
                            30
static uint8 writeByte;
static uint8 rxBytes;
static uint8 ramData[4];
static uint8 aesKey[AES_BLOCK_SIZE];
static uint8 nonce[AES_BLOCK_SIZE];
// 1) Make sure radio is in IDLE state
trxSpiCmdStrobe(CC120X_SIDLE);
// 2) Flush RX FIFO to reset pointers
trxSpiCmdStrobe(CC120X_SFRX);
// 3) Set radio in RX
trxSpiCmdStrobe(CC120X_SRX);
// Wait for packet
while(!packetSemaphore);
// Check available bytes in the RXFIFO
ccl20xSpiReadReg(CCl20X_NUM_RXBYTES, &rxBytes,1);
// 4) Set MARC_SPARE.AES_COMMAND to 0x0A (AES RXFIFO)
writeByte = 0x0A;
ccl20xSpiWriteReg(CCl20X_MARC_SPARE, &writeByte,1);
// 5) Write AES key to extendend regiater space address 0xE0
ccl20xSpiWriteReg(CCl20X_AES_KEY15, aesKey, sizeof(aesKey));
// 6) Enable SPI direct memory access (SPI_DIRECT_ACCESS_CFG = 1)
writeByte = 0x20;
ccl20xSpiWriteReg(CCl20X_SERIAL_STATUS,&writeByte,1);
// 7) Write AES TXFIFO marc paramenters to RAM: (may need to zero RAM content)
// TXFIFO start pointer @ 0x38F0 (extended memory space, Free Area 0x3EF0) (word length 2B)
// TXFIFO packet size & 0x38F2 (extended memory space, Free Area 0x3EF2) (word length 2B)
ramData[0] = 0x00;
                                // TXFIFO start pointer
ramData[1] = 0x00;
                                // zero-pad due to word write in ram
ramData[2] = rxBytes-2;
                                // payload = number of bytes in the FIFO - appended bytes
ramData[3] = 0x00;
                                 // zero-pad
trx16BitRegAccess((RADIO_BURST_ACCESS|RADIO_WRITE_ACCESS),0x3E,0xF0,ramData,sizeof(ramData));
// 8) Write nonce vector (16B) to 0x3E80 extended memory space.
// This vector has to be written byte reversed to what will be put in the AES BUFFER.
// AES command will rotate the vector on execution
trx16BitRegAccess((RADIO_BURST_ACCESS|RADIO_WRITE_ACCESS),0x3E,0x80,nonce,sizeof(nonce));
// 9) Disable SPI direct memory access (SPI_DIRECT_ACCESS_CFG = 0)
writeByte = 0x00;
ccl20xSpiWriteReg(CCl20X_SERIAL_STATUS,&writeByte,1);
// 10) Execute AES command by issuing IDLE strobe (radio must be in IDLE state already)
trxSpiCmdStrobe(CC120X_SIDLE);
// 11) Wait for GPIOO to go low, indicating command finished
// Assumes AES_COMMAND_ACTIVE(0x16) on GPIO0 sets aesSemaphore on falling edge interrupt
while(!aesSemaphore);
```



## 6 References

• CC120X Low-Power High Performance Sub-1 GHz RF Transceivers User's Guide (SWRU346)

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